Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4856000	@ad>"20030316" @rlad>"20030316" @pt1d>"20030316"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/15 19:00
L2	219	encapsula\$ with coolant not L1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:00
L3	219	encapsula\$ with coolant not L1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2007/04/15 19:00
L4	46933	automatic adj transmission not L1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/15 19:07
L5	0	L4 and 3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:01
L6	1490	257/714.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:06
L7	287421	encaps\$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/15 19:06
L10	104	7 and 6 .	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:08
L11	0	4 and 6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:07
L12	. 21	auto\$6 and transmission and 6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/15 19:00
L21	42	control adj module and semiconductor and 4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:19
L23	26	(cool\$8 heat\$8 fluid\$) and 21	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:23
L24	7451	transmission adj fluid not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:23
L25		("438"/\$.ccls. "257"/\$.ccls.) and 24	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ÓN	2007/04/15 19:35
L26	2	(*20010022404*).PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 19:34

4/15/2007 9:03:25 PM

L27	363920	("438"/\$.ccls. "257"/\$.ccls.) not 1	US-PGPUB;	OR	ON	2007/04/15 19:35
-2,	000020	(100)00000 00 100000 00 100000 00 100000 00 100000 00	USPAT; FPRS; EPO; JPO; DERWENT;			
			IBM_TDB		ON	2007/04/15 20:15
. 28	. 67	(adhesive with metal with filler with inorganic) and thermoset\$ and epoxy not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/04/15 20.15
•			IBM_TDB		-	2007/04/45 40:44
L29	75	molded adj (heatsink heat\$1sink heat adj sink) not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:41
L30	2510	circuit adj board with (fluid coolant) not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:4
L31	450	circuit adj board with (cooling adj fluid coolant) not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/04/15 19:45
i			IBM_TDB	00	011	2007/04/45 40:41
L32	34	encaps\$8 and 31	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 19:43
L33	1	(US-20010022404-\$).did.	US-PGPUB	OR	ON	2007/04/15 20:09
L34	0	28 and 33	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 20:05
L35	0	33 and (metal with filler with inorganic) and thermoset\$ and epoxy not 1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/04/15 20:10
	ļ		IBM_TOB		ļ	
L36	18	insulat\$ with adhesive and 28	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 20:1
S1	1	"10801697".rlan. or ("10".src. and "801697".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2007/04/12 20:3
S4	50	("20010003373" "20010005048" "20010020741" "20010022404" "20010031828" "20020121690" "20030 038366" "20030098504" "20030137032" "20030164540" "20030197260" "20030201525" "20040045614" "3564114" "4763188" "4982265" "5040994" "5138438" "5191404" "5218515" "52218555" "5285104" "53 19522" "5587341" "5685361" "5692558" "5708298" "5793101" "5880403" "59169585" "6057778" "62443 31" "6262488" "6297548" "6345238" "6424030" "6429513" "6457484" "6521993" "5548895" "658626" "6627997" "6650007" "6693346" "6695748" "6715510" "6730543" "6739042" "6781241" "6798056").PN.	US-PGPUB;	OR	ON	2007/04/12 21:1
S5	1	(conventional\$ prior adj art well adj known incorporated) and S1	US-PGPUB; USPAT	OR	ON	2007/04/12 20:5
S6	,12	transmission and S4	US-PGPUB; US-PGPUB; US-PAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/12 21:1
S7	4848221	@ad>"20030316" @rlad>"20030316" @pt1d>"20030316"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/12 21:1
S9	3339	mechatronic\$ not S7	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR .	ON	2007/04/12 21:1
S10	46933	automatic adj transmission not S7	IBM_TDB US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB		ON	2007/04/12 21:

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S11	19	S9 and S10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/12 21:24
S12	. 7	S9 adj control adj module	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/12 21:25
S13	34	("20020073538" "4554505" "4744009" "5219377" "5224387" "5305663" "5311398" "5606198" "5611372" "5662007" "5685803" "5692909" "5733598" "5823070" "5847282" "6049975" "6056908" "6086509" "6155119" "6160708" "6164160" "6171207" "6209399" "6530856" "6612202" "RE33604").PN. OR ("2001/0005048" "2002/0073538" "2002/0088304" "2002/0111730" "6612202" "6739042").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 21:51
S14	. 27	S13 not S7	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:16
S15	4848221	@ad> "20030316" @rlad> "20030316" @pt1d> "20030316"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 12:16
S16	410	flexible adj ceramic not S15	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:35
S17	167495	circuit adj board not S15	US-PGPUB; USPAT; USOCR	OR .	ON	2007/04/13 12:17
S18	2	S16 with S17	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:17
S19	7451	transmission adj fluid not \$15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 12:26
S20	3339	mechatronic\$ not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 12:27
S21		S20 and S19	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON.	2007/04/13 12:29
\$22	110401	cool\$ with fluid not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 12:30
S23	6	S20 and S22	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/13 12:30
S24	579	flex\$5 with circuit adj board with ceramic not S15	US-PGPUB; USPAT; USOCR	OR	ON.	2007/04/13 12:37
\$25	318793	wrap\$5 not S15	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:36
S26	2	S24 with S25	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:36
S27	195	flex\$5 with circuit adj board with \$25	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 12:37
S28	1	automatic adj transmission and \$27	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 13:16
S29	19	(leadframe lead adj frame lead\$1frame) and automatic adj transmission not S15	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 13:27
S31		board with wrap\$5 with (heatsink heat\$1sink heat adj sink) not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/15 19:38

S32	903	(Ishii-Toshiaki Tsuyuno-Nobutake Masuda-Mitsuhiro Urushiwara-Noriyoshi Matsushita-Akira).in. not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/04/13 14:14
			IBM_TDB			
S33		polyimide and S32	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/04/13 14:16
			IBM_TDB ·			
S34	20	(wrap\$5 bend\$5) and S32	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 14:18
S35	10	flex\$5 with board and S32	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 16:07
S36	200	ceramic near2 board with flex\$5 near2 board not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 16:28
S37	3	*06216532*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON _.	2007/04/13 16:43
S38	1	1994-289113.NRAN.	DERWENT	OR	ON	2007/04/13 16:28
S39	92	SEGAWA-MASAO.in.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON [*]	2007/04/13 16:51
S40	1	*61030093*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 16:51
S41	1	1986-084223.NRAN.	DERWENT	OR	ON	2007/04/13 16:51
S42	1	1986-084223.NRAN.	DERWENT	OR	ON	2007/04/13 16:57
S43	. 1	*61030093*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 17:09
S44	1	("61030093").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/13 17:03
S45		stiff adj ceramic near2 board not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 17:03
S46	16	(stiff rigid) adj ceramic near2 board not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/13 17:03
S47	0	59-150909	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON.	2007/04/13 17:09
S48	o	*590150909*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 17:09

				,		
S49	1	*59150909*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 18:00
S50	1	(US-6049975-\$).did.	USPAT	OR	ON	2007/04/13 18:01
S51	1	(heat\$8 cool\$8 temperat\$) and S50	US-PGPUB; USPAT;	OR	ON	2007/04/14 11:48
			FPRS; EPO; JPO; DERWENT; IBM_TDB			:
S52	130	(ceramic with board) and sony.as. not S15	US-PGPUB; USPAT; FPRS;	OR	ON	2007/04/13 19:00
	•		EPO; JPO; DERWENT; IBM_TDB			
S53	56	ceramic and (flex\$5 with board) and sony.as. not S15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/13 19:01
S54	28.	("4429349" "4724611" "4903169" "5219377").PN. OR ("6049975").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 19:20
S55	21	S54 not S15	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 21:36
S56	4	polyimide and S55	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 19:21
S57	12	(US-20020111730-\$ or US-20020088304-\$ or US-20020032093-\$ or US-20020126951-\$).did. or (US-6548895-\$ or US-6530856-\$ or US-6155119-\$ or US-6049975-\$ or US-5823070-\$ or US-5831788-\$ or US-5855229-\$).did. or (JP-61030093-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2007/04/13 21:36
S58	0	polyimide and S57 and (thermoset\$ thermo\$1set\$5 thermo adj set\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 22:01
S59		(*20030137032*).PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/13 21:49
S60	0	polyamide with polyimide and S57	US-PGPUB; USPAT; .FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 21:50
S61	. 2	polyimide and \$57	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2007/04/13 21:57
S62		polyimide with polyamide with flex\$5 adj circuit adj board not \$15	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 21:58
S63		thermoset\$ and S62	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 21:58
S64	0	S62 and (thermoset\$ thermo\$1set\$4 thermo adj (set sett\$4))	US-PGPUB; USPAT; USOCR	OR .	ON	2007/04/13 22:00
S65	. 0	polyimide and S57 and (thermoset\$ thermo\$1set\$5 thermo adj (set sett\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/13 22:06
S66	44	(US-20020111730-\$ or US-20020088304-\$ or US-20020032093-\$ or US-20020126951-\$ or US-20030137032-\$ or US-20010003373-\$ or US-20010022404-\$ or US-20010005048-\$ or US-20020073538-\$ or US-20040118466-\$ or US-20040045614-\$ or US-20030226527-\$ or US-20030168043-\$),did. or (US-6548895-\$ or US-6530856-\$ or US-6155119-\$ or US-6049975-\$ or US-5823070-\$ or US-5831788-\$ or US-5855229-\$ or US-4763188-\$ or US-6739042-\$ or US-6612202-\$ or US-6164160-\$ or US-6160708-\$ or US-6056908-\$ or US-5733598-\$ or US-5692909-\$ or US-562007-\$ or US-561372-\$ or US-5055362-\$ or US-655385-\$ or US-5615510-\$ or US-6595748-\$ or US-5276584-\$ or US-5267516-\$ or US-7047939-\$ or US-5023098-\$ or US-5266746-\$,did. or (WO-2055904-\$),did. or (JP-61030093-\$ or US-5963427-\$ or JP-06216532-\$),did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/13 22:06
S67	3	polyimide and \$66 and (thermoset\$ thermo\$1set\$5 thermo adj (set sett\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/14 10:54
S68	1	(US-6049975-\$).did.	USPAT	OR	ON	2007/04/14 10:55

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S69	1	("70" with resin) and S68	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/14 10:56
S70	. 13	(US-20020111730-\$ or US-20020088304-\$ or US-20020032093-\$ or US-20020126951-\$).did. or (US-6548895-\$ or US-6530856-\$ or US-6155119-\$ or US-6049975-\$ or US-5823070-\$ or US-5831788-\$ or US-5855229-\$ or US-6023098-\$).did. or (JP-61030093-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2007/04/14 11:07
S71	8	transmission and \$70	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:25
S72	4848221	@ad> "20030316" @rlad> "20030316" @pt1d> "20030316"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:25
S73	46933	automatic adj transmission not S72	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	OŅ .	2007/04/14 11:25
S74	46933	S73	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/04/14 11:26
S75	204184	encapsula\$5 not \$72	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:26
S76	20204	(board chip die) with S75	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:26
S77	8	S73 and S76	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR :	ON	2007/04/14 11:26
S78		(US-20030137032-\$ or US-20010003373-\$ or US-20010022404-\$ or US-20010005048-\$ or US-200200111730-\$ or US-20020083304-\$ or US-200200338-\$ or US-2002001116804-\$ or US-2002003203-\$ or US-2002003203-\$ or US-20030168043-\$ or US-20020032652-\$ or US-602205257-\$ or US-6020205257-\$ or US-6020205257-\$ or US-60200205590-\$ or US-60200205590-\$ or US-602020-\$ or US-6530856-\$ or US-6164160-\$ or US-6160708-\$ or US-615119-\$ or US-605908-\$ or US-6049975-\$ or US-6530856-\$ or US-6164160-\$ or US-6160708-\$ or US-562007-\$ or US-561372-\$ or US-503563-\$ or US-6059382-\$ or US-5832578-\$ or US-6715510-\$ or US-562007-\$ or US-56	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/14 11:30
S79	44 -	S78 not S77	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:40
S80	28	S79 and transmission	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:40
S81	1	(US-5823070-\$).dld.	USPAT ·	OR	ON	2007/04/14 11:47
S82	1	(heat\$8 cool\$8 temperat\$) and S81	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 11:48
S83		(oil fluid) and S81	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 18:59